



**LP5 SiGe**  
Product Environmental Data Sheet

20 Alpha Rd  
Chelmsford MA 01824  
Tel: (978) 250-3343  
Fax: (978) 250-3373

<b>Product Information</b>	<b>Date/Time Revision:</b>	February 25, 2005					
	<b>Manufacture site:</b>	Chelmsford MA					
	<b>Product Number</b>	Generic: LP5, Plastic Encapsulated Microcircuit					
	<b>Product Name</b>	Surface Mount SiGe Semiconductor					
	<b>Product Mass</b>	Grams:	Min 0.055836	Max 0.068244	Nominal	0.06204	
	<b>Product Note</b>						

**Material Composition Information**

Component	Material Part Name	Material	Material Trade Name	Material Mass (g) Minimum	Material Mass (g) Maximum	Percent of product (%) Minimum	Percent of product (%) Maximum
A	Lead Frame	Metal	Copper Lead Frame	0.0223	0.0307	40.0%	45.0%
B	Mold Compound	Polymer	Sumitomo EME7730LF	0.0257	0.0341	46.0%	50.0%
C	Epoxy, Die attach	Epoxy	Sumitomo CRM1076DJ	0.0006	0.0014	1.0%	2.0%
D	Semiconductor, SiGe	Non- metal, Non- polymer	Silicon/Germanium	0.0006	0.0014	1.0%	2.0%
E	Bond Wire, Gold	Metal	Wire	0.0003	0.0007	0.5%	1.0%
F	Solder, Lead Finish	Sn/Pb	Plating Coat	0.0006	0.0014	1.0%	2.0%
Substance	Substance Name	Substance CAS#	Substance Note	Substance Mass (g) Minimum	Substance Mass (g) Maximum	Percent of Substance (%) Minimum	Percent of Substance (%) Maximum
<b>A</b>	<b>Copper Lead Frame</b>						
A1	Cu	7440-50-8	n/a	0.021664	0.030096	97.00%	98.00%
A2	Fe	7439-89-6	n/a	0.000591	0.000819	2.30%	2.40%
A3	Zn	7440-66-6	n/a	0.000001	0.000002	0.11%	0.13%
A4	P	7723-14-0	n/a	0.000000	0.000001	0.02%	0.04%
<b>B</b>	<b>Mold Compound</b>						
B1	Silica Fused	60676-86-0	n/a	0.019263	0.032416	75.00%	95.00%
B2	Epoxy Resin	(Trade Secret)	n/a	0.001027	0.003412	4.00%	10.00%
B3	Phenol Resin	(Trade Secret)	n/a	0.000257	0.002047	1.00%	6.00%
B4	Antimony Trioxide	1309-64-4	n/a	0.000026	0.000307	0.10%	0.90%
B5	Brominated Epoxy Resin	40039-93-8	n/a	0.002568	0.000341	10.00%	1.00%
B6	Carbon Black	1333-86-4	n/a	0.000026	0.000171	0.10%	0.50%
<b>C</b>	<b>Die Attach Epoxy</b>						
C1	Silver	7440-22-4	n/a	0.000363	0.001160	65.00%	85.00%
C2	Epoxy Resin	9003-36-5	n/a	0.000084	0.000341	15.00%	25.00%
C3	t-Butyl phenyl glycidyl ether	3101-60-8	n/a	0.000028	0.000136	5.00%	10.00%
C4	Phenolic hardener	92-88-6	n/a	0.000006	0.000027	1.00%	2.00%
C5	Butyl cellosolve acetate	112-07-2	n/a	0.000003	0.000020	0.50%	1.50%
<b>D</b>	<b>SiGe Semiconductor</b>						
D1	Si	7440-21-3	n/a	0.000419	0.001160	75.00%	85.00%
D2	Ge	7440-56-4	n/a	0.000084	0.000341	15.00%	25.00%
<b>E</b>	<b>Bond Wire</b>						
E1	Gold (Au)	7440-57-5	Die Attach, wirebond	0.000279	0.000682	99.99%	100.00%
<b>F</b>	<b>Solder</b>						
F1	Tin	7440-31-5	Tin, Lead solder	0.000469	0.001174	84.00%	86.00%
F2	Lead	7439-92-1	Tin, Lead solder	0.000078	0.000218	14.00%	16.00%

**NOTE:** CAS is not available for proprietary substances. All percentages are calculated from mass data declared. Material trade names are not applicable to some common materials for constant composition. When CAS is unavailable, vendor supplier comments such as PROPRIATARY or TRADE SECRET will be documented

**Flammability**

The plastic mold compound used for this device has been tested for flammability of plastic materials used for parts in devices and appliances and is classified as UL-94 V0.

**Absence of Hazardous Substances**

Our material composition policy is to declare all substances intentionally added in our products and documented by our vendors. Additionally we confirm the following regulated substances known to be in electronics are not intentionally added or knowingly present in our semiconductor products or product packaging: Cadmium and cadmium compounds, mercury and mercury compounds, hexavalent chromium compounds, polychlorinated biphenyl (PCB), polychlorinated naphthalenes (PCN), polybrominated diphenyl ether (PBDE), decabromodiphenyl ether (DecaBDE), short chain paraffins (CP) (C10-13) (Cl = 50 wt% or more), mirex (perchlordecone), TBBP-A-bis, organic tin compounds (tributyl tin compounds / triphenyl tin compounds) Asbestos, formaldehyde and Azo compounds.

**Product Life Cycle Information**

Our devices are often incorporated into printed circuit boards and then assembled with other parts into electronic systems. In the U.S.A., end-of-life printed circuit boards (waste), are considered scrap metal by the Environmental Protection Agency (EPA) when they are recycled (USEPA Mgt. memo, Regulatory Status or Printed Circuit Boards, Aug 26, 1992). If any of our products are disposed of as part of a printed circuit board, the entire assembly is treated as scrap metal. Approved printed circuit recycling companies either have proper facilities or have access to secondary metal smelters and refiners which can safely recycle scrap electronic components or assemblies

The information presented in this document is believed accurate and reliable. The information provided is a result of review of numerous sources including vendor submitted datasheets. Data is the most current available to Hittite Microwave Corporation at the time of preparation and is issued as a matter of reference information only. No warranty as to accuracy or completeness is expressed or implied. The information in this document is subject to change without notice.



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Component	Material Part Name	Material	Material Trade Name	Material Mass (g) Minimum	Material Mass (g) Maximum	Percent of product (%) Minimum	Percent of product (%) Maximum
A	Lead Frame	Metal	Copper Lead Frame	0.0223	0.0307	40.0%	45.0%
B	Mold Compound	Polymer	Sumitomo G770	0.0257	0.0341	46.0%	50.0%
C	Epoxy, Die attach	Epoxy	Sumitomo CRM1076DJ	0.0006	0.0014	1.0%	2.0%
D	Semiconductor, SiGe	Non- metal, Non- polymer	Silicon/Germanium	0.0006	0.0014	1.0%	2.0%
E	Bond Wire, Gold	Metal	Wire	0.0003	0.0007	0.5%	1.0%
F	Lead Finish	Sn	Plating Coat	0.0006	0.0014	1.0%	2.0%
Substance	Substance Name	Substance CAS#	Substance Note	Substance Mass (g) Minimum	Substance Mass (g) Maximum	Percent of Substance (%) Minimum	Percent of Substance (%) Maximum
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A3	Zn	7440-66-6	n/a	0.000001	0.000002	0.11%	0.13%
A4	P	7723-14-0	n/a	0.000000	0.000001	0.02%	0.04%
<b>B</b>	<b>Mold Compound</b>						
B1	Silica Fused	60676-86-0	n/a	0.019263	0.032416	75.00%	95.00%
B2	Epoxy Resin A	(Trade Secret)	n/a	0.000257	0.001706	1.00%	5.00%
B3	Epoxy Resin B	(Trade Secret)	n/a	0.000257	0.001706	1.00%	5.00%
B4	Phenol Resin A	(Trade Secret)	n/a	0.000257	0.001706	1.00%	5.00%
B5	Phenol Resin B	(Trade Secret)	n/a	0.000257	0.001706	1.00%	5.00%
B6	Metal Hydroxide	(Trade Secret)	n/a	0.000128	0.000853	0.50%	2.50%
B7	Carbon Black	1333-86-4	n/a	0.000026	0.000171	0.10%	0.50%
<b>C</b>	<b>Die Attach Epoxy</b>						
C1	Silver	7440-22-4	n/a	0.000363	0.001160	65.00%	85.00%
C2	Epoxy Resin	9003-36-5	n/a	0.000084	0.000341	15.00%	25.00%
C3	t-Butyl phenyl glycidyl ether	3101-60-8	n/a	0.000028	0.000136	5.00%	10.00%
C4	Phenolic hardener	92-88-6	n/a	0.000006	0.000027	1.00%	2.00%
C5	Butyl cellosolve acetate	112-07-2	n/a	0.000003	0.000020	0.50%	1.50%
<b>D</b>	<b>SiGe Semiconductor</b>						
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<b>E</b>	<b>Bond Wire</b>						
E1	Gold (Au)	7440-57-5	Die Attach, wirebond	0.000279	0.000682	99.99%	100.00%
<b>F</b>	<b>Solder</b>						
F1	Tin	7440-31-5	Tin, Lead solder	0.000558	0.001365	99.99%	100.00%

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